Product Bulletin

Document #: PB24187X
Issue Date: 13 Aug 2021

Title of Change:	Change of Die Attach Epoxy for XGS12M products
Effective date:	13 Aug 2021
Contact information:	Contact your local ON Semiconductor Sales Office or Danny.Scheffer@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
None	MMT, Thailand

Description and Purpose:

The purpose for this change of new die attach epoxy is to eliminate stain under glass issue to continue production line for all XGS12M product family. There is no appearance difference and with better quality performance.

List of Affected Standard Parts:

***Note**: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

NOIX3SN012KB-LTI	NOIX3SN012KB-LTI1	NOIX3SE012KB-LTI
NOIX3SE012KB-LTI1	NOIX1SE012KB-LTI1	NOIX1SE012KB-LTI
NOIX1SE8000B-LTI1	NOIX1SE8000B-LTI	NOIX1SE9400B-LTI1
NOIX1SE9400B-LTI	NOIX1SF012KB-LTI1	NOIX1SF012KB-LTI
NOIX1SN012KB-LTI1	NOIX1SN012KB-LTI	NOIX1SN8000B-LTI1
NOIX1SN8000B-LTI	NOIX1SN9400B-LTI1	NOIX1SN9400B-LTI
NOIX2SE8000B-LTI1	NOIX2SE8000B-LTI	NOIX2SE9400B-LTI1
NOIX2SE9400B-LTI	NOIX2SF8000B-LTI1	NOIX2SF8000B-LTI
NOIX2SN8000B-LTI1	NOIX2SN8000B-LTI	NOIX2SN9400B-LTI1
NOIX2SN9400B-LTI		